

App. No. 09/196,185

Amendment dated July 6, 2006

Reply to Office action dated Apr. 6, 2006

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Atty. Docket No. AB-1758 US

OPP 980427 US

JUL 0 5 2006**REMARKS/ARGUMENTS**

The above amendment and the following remarks are in reply to the Office action of 04/06/06. In light of this reply, reconsideration and further examination of this application are respectfully requested.

Twenty-one claims (1-3, 6-14 and 18-26) were pending in this application. Of these, fourteen claims (1-3, 6-13 and 18-20) have previously been withdrawn from consideration. In the above amendment, two claims (14 and 26) were amended. Accordingly, 7 claims (14 and 21-26) remain pending for reconsideration and further examination.

In Section 2 of the Office action, the Examiner rejected claims 14 and 21-26 under 35 U.S.C. 103(a) as being unpatentable over US 5,852,481 (Hwang) in view of US 5,162,933 (Kakuda et al.) and JP 05241173 (Yatabe et al.)

In light of the above amendment to independent claims 14 and 26 and the remarks that follow, it is respectfully submitted that this rejection has been rendered moot.

In particular, claims 14 and 26 now include the following respective limitations:

Claim 14: "wherein ... at least one of the gate wire and the data wire comprises a metal layer and a metal nitride layer, the metal of the metal nitride layer being the same as that of the metal layer and substantially inert to an etchant used for etching the transparent layer so as to prevent the at least one gate pad and data wire from being eroded by the etchant, and

the transparent conductive layer directly contacts an upper surface of the metal nitride layer in the first and the second holes"; and,

Claim 26: "wherein ... at least one of the gate wire and the data wire comprises a main layer and a supplemental layer, the main layer comprising a metal or a metal alloy and the supplemental layer comprising a metal nitride or a metal alloy nitride in which the metal or metal alloy is the same as that of the main layer, and

the transparent conductive layer directly contacts an upper surface of the supplemental layer in the first and the second holes."

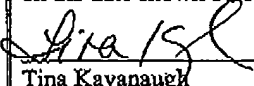
An examination of each of Hwang, Kakuda et al. and Yatabe et al. reveals that none of these teaches or suggests the foregoing limitations, whether taken singly or in any combination.

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In light of the above amendment and remarks, it is respectfully submitted that claims 14 and 21-26 are now allowable over the art of record. Applicant therefore respectfully requests that a timely Notice of Allowance be issued in this case.

If there are any questions regarding this Reply, the Examiner is invited to contact the undersigned at the number indicated below.

Certification of Facsimile Transmission	
I hereby certify that this paper is being facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below.	
 Tina Kavanaugh	July 5, 2006 Date of Signature

Respectfully submitted,



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